

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2a  
Ru amlt  
nchopm  
10-0-01

In re application of :  
Masao YOSHIDA et al. :  
Serial No. [NEW] : ATTN: APPLICATION BRANCH  
Filed August 17, 2001 : Attorney Docket No. 2001-1152  
POLISHING APPARATUS

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents,  
Washington, DC 20231

Sir:

**THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975**

Kindly amend the above-identified application as follows:

IN THE SPECIFICATION:

Page 1, above the title of the invention please delete "DESCRIPTION".

Please replace the paragraph beginning at page 3, line 20, with the following rewritten paragraph:

To achieve the first object described above, according to a first aspect of the present invention, there is provided a polishing apparatus for polishing a workpiece such as a semiconductor wafer, comprising: a processing section for polishing a workpiece; a receiving section for supplying a workpiece to be polished to the processing section and/or receiving a polished workpiece; and a clean chamber disposed between the processing section and the receiving section and including a partition with a shutter which separates the processing section and the receiving section from each other. The receiving section serves to supply a workpiece to be polished to the processing section,

al

00344100701  
10/20/01